



DB-S Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 21.87%	Copper (Cu)	7440-50-8	93.990	99.98	218,623.3
	Phosphorus (P)	7723-14-0	0.0009	0.0010	2.2
	Arsenic (As)	7440-38-2	0.0009	0.0010	2.2
	Tin (Sn)	7440-31-5	0.0009	0.0010	2.2
	Oxygen (O)	7782-44-7	0.0005	0.0005	1.1
	Sulfur (S)	7704-34-9	0.0113	0.0120	26.2
	Iron (Fe)	7439-89-6	0.0006	0.0007	1.4
	Nickel (Ni)	7440-02-0	0.0003	0.0003	0.7
	Bismuth (Bi)	7440-69-9	0.0019	0.0020	4.4
	Antimony (Sb)	1309-64-4	0.0019	0.0020	4.4
	Lead (Pb)	7439-92-1	0.0005	0.0005	1.1
	Zinc (Zn)	7440-66-6	0.0003	0.0003	0.7
	Total		94.01		
Solder Wafer 1.02%	Lead (Pb)	7439-92-1	4.06	92.48	9,443.7
	Tin (Sn)	7440-31-5	0.22	5.01	511.7
	Silver (Ag)	7440-22-4	0.11	2.51	255.9
		Total		4.39	
Chip 0.84%	Silicon (Si)	7440-21-3	3.60	100.00	8,373.7
		Total		3.60	
Molding 76.06%	Silica (SiO ₂)	14808-60-7	238.71	73.00	555,246.0
	Epoxy resin	29690-82-2	55.59	17.00	129,303.9
	Phenolic resin	9003-35-4	28.78	8.80	66,933.8
	Antimony trioxide	1309-64-4	2.29	0.70	5,324.3
	Brominated epoxy	40039-93-8	1.50	0.46	3,498.8
	Carbon Black	1333-86-4	0.13	0.04	304.2
	Total		327.00		
Plating 0.21%	Tin (Sn)	7440-31-5	0.92	100.00	2,134.4
		Total		0.92	
	Total mass (mg)		429.92		